

II. Please replace the original ABSTRACT in its entirety, page 25, with the following rewritten ABSTRACT:

ABSTRACT

A method for removing polymer residues on sidewalls of metal lines is provided where a wafer is immersed in a stripping solution for a first immersion time. Next, the wafer is removed from the stripping solution and allowed to drip. Then the wafer is immersed in a first organic solvent for removing the stripping solution left on the wafer. The wafer is then removed from the first organic solvent and allowed to drip. Next, the wafer is immersed in a water flow for removing the stripping solution and the first organic solvent left on the wafer. Finally, water left on the wafer is removed.